

CQFP

Ceramic Quad Flat Pack Package (CQFP)

Amkor Technology is continuing to service this established industry package. The Amkor Technology CQFP capability provides you, the customer, with a wide range of lead counts and body sizes available from various suppliers. The CQFP is a hermetic package consisting of two pieces of dry pressed ceramic surrounding a "gullwing" formed leadframe. The ceramic / LF / ceramic system is held together hermetically by glass. The frit lid is sealed/reflowed over the package cavity at temperatures between 400° - 460° Centigrade.

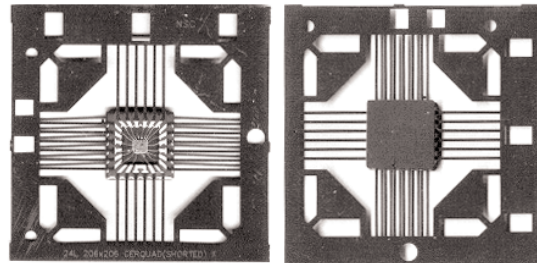
Applications:

Along with the other standard industry packages, the CQFP has a proven track record and is still being used by semiconductor technologies such as: Digital to Analog converters, Microwave, Logic, Memory, Microcontrollers, and Video controllers. Some end applications are: Military electronics, Commercial electronics, Automotive and Telecommunications.

Features:

The CQFP offers a variety of features:

- Square package body
- 14-256 lead count, 25-50 mil lead pitch's
- Hermetic package
- High thermal conductive ceramic
- Solder Plate lead finish
- JEDEC standard compliant
- Wide selection of available cavity sizes to meet most die size needs
- Commercial or full Military flows



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